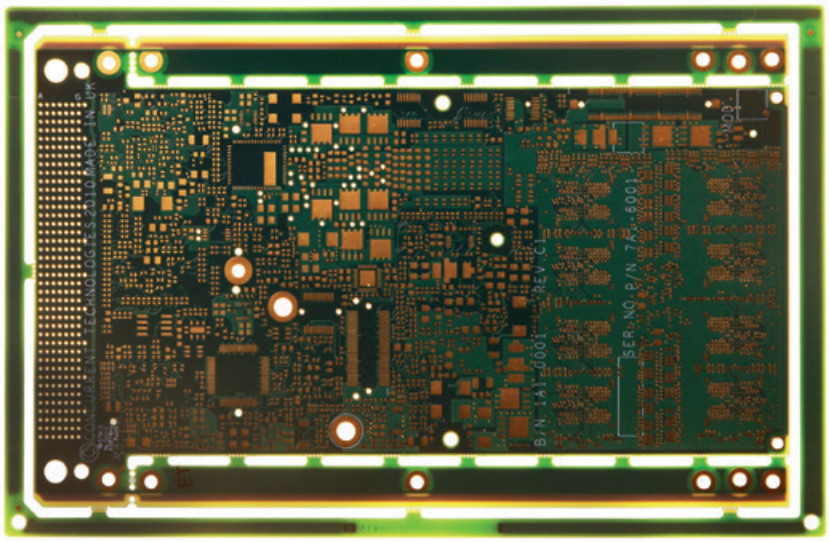
NCAB GROUP
Integrated PCB Production

PCB PORTFOLIO

Multilayer HDI RF IMS Flexible Rigid-Flex Semi-Flex Single & Double sided

May 2016



HDI – High Density Interconnect

NCAB has been building HDI boards for over 20 years. Our factory base has a broad experience producing HDI boards for different market applications. The factories, in concert with our world-wide technical organization, bring a comprehensive knowledge of the requirements and manufacturing methodologies required for successful HDI production. NCAB Group technical support begins at the design phase of HDI products where we can provide engineering expertise to design teams to improve manufacturability and lower overall product costs. Over 15% of our global sales are in the HDI segment which gives us the opportunity to attract the best factories in the world. We can manage local NPI and quick-turns for proof of design and bring the product to volume production off-shore seamlessly, providing a streamlined process that brings new products to market faster.

HDI PCBs – TECHNICAL SPECIFICATION

FEATURE	NCAB´S TECHNICAL SPECIFICATION
Number of layers	4 – 22 layers standard, 30 layers advanced
Technology highlights	Multilayer boards with a higher connection pad density than standard boards, with finer lines/spaces, smaller via holes and capture pads allowing microvias to only penetrate select layers and also be placed in surface pads.
HDI builds	1+n+1, 2+N+2, 3+N+3, 4+n+4, any layer in R&D
Materials	Halogen-free FR-4, FR-4 high performance, Halogen-free FR-4, Rogers
Copper weights (finished)	18um – 70um
Minimum track and gap	0.075mm / 0.075mm
PCB thickness	0.40mm – 3.20mm
Maximum dimensions	610mm x 450mm; dependant upon laser drilling machine
Surface finishes available	OSP, ENIG, Immersion Tin, Immersion Silver, Electrolytic gold, Gold fingers
Minimum mechanical drill	0.15mm
Minimum laser drill	0.10mm standard, 0.075mm advanced
DFM guides	Download our Newsletter about HDI with design tips